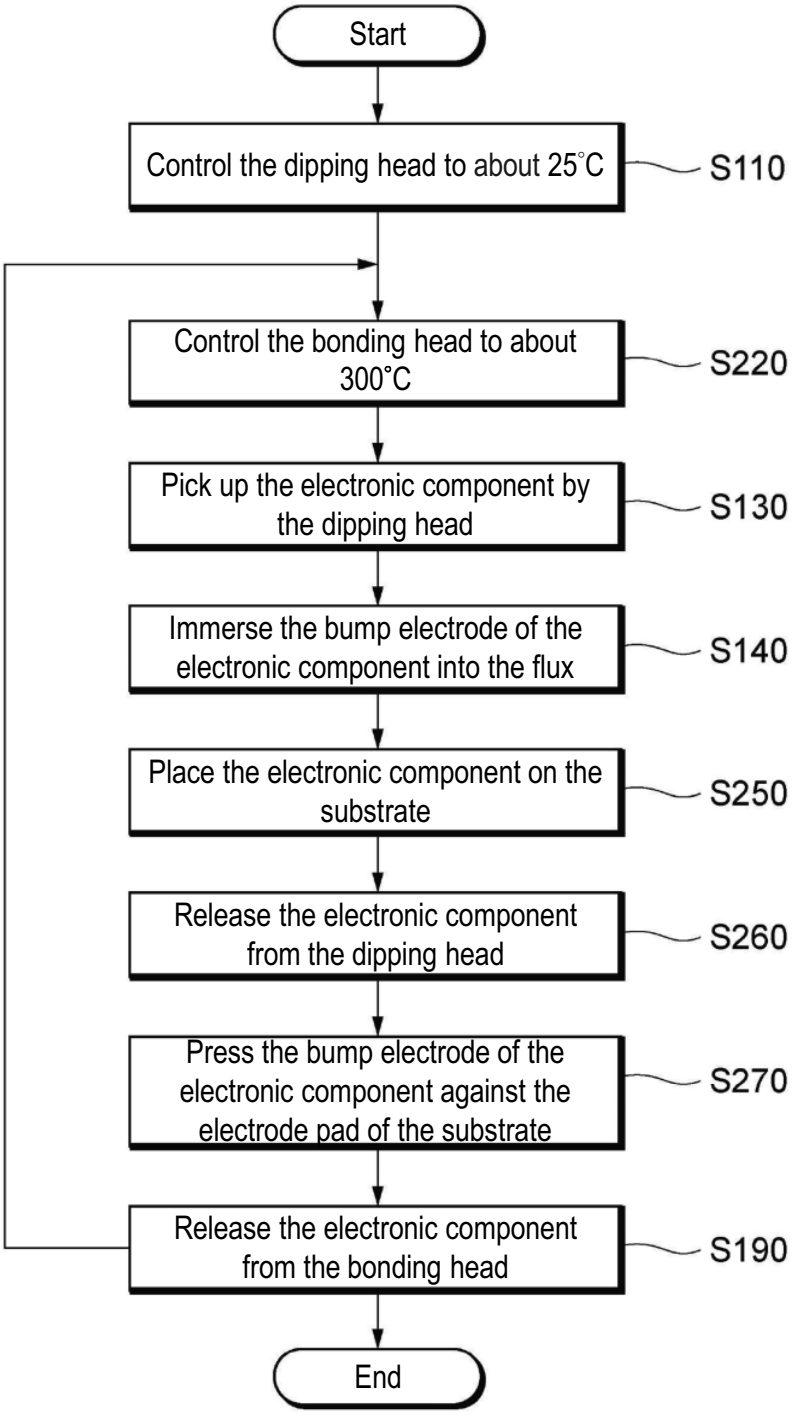

Start
Control the dipping head to about 25°C
S110
Control the bonding head to about 300°C
S220
Pick up the electronic component by the dipping head
S130
Immerse the bump electrode of the electronic component into the flux
S140
Place the electronic component on the substrate
S250
Release the electronic component from the dipping head
S260
Press the bump electrode of the electronic component against the electrode pad of the substrate
S270
Release the electronic component from the bonding head
S190
End

FIG. 8